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Flexible electronic skin with nanostructured interfaces via flipping over electroless deposited metal electrodes

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Abstract

A novel and simple method was developed to quickly pattern and transfer electrodes with nanostructures for fabricating flexible electronic skin (E-skin). A nano/micro-structure embedded Cu electrode can be fabricated from a solution process-based electroless deposition (ELD) on a frosted plastic substrate and subsequently flipped over with an adhesive tape. The fine nano/microstructures on the Cu layer benefit the pressure-electric response of the pressure sensor, demonstrated a high sensitivity: 2.22 kPa^{-1} . This fabricated flexible E-skin can be used for monitoring human physiological signals, such as wrist pulse and thumb bending. This fabrication

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